

**Product / Package Information**

Package	LQFP
Body Size (mm)	10 X 10 X 1.4
Lead Count	64
Terminal Finish	100 Sn

**Environmental Information**

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

**Materials Declaration**

**Molding Compound**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica fused	60676-86-0	2.20E-01	86.91	869100	62.20	621976
Thermosets	Epoxy & Phenol resin	Proprietary	3.24E-02	12.78	127800	9.15	91461
Other inorganic materials	Carbon black	1333-86-4	7.86E-04	0.31	3100	0.22	2219
Subtotal			2.54 E-01	100.00	1000000	71.57	715655

**Leadframe**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	7.24E-02	97.50	975000	20.43	204327
Copper & its alloys	Iron	7439-89-6	1.75E-03	2.35	23500	0.49	4925
Copper & its alloys	Zinc	7440-66-6	8.91E-05	0.12	1200	0.03	251
Copper & its alloys	Phosphorus	7723-14-0	2.23E-05	0.03	300	0.01	63
Subtotal			7.43 E-02	100.00	1000000	20.96	209566

**Internal Leadframe Plating**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious Metals	Silver	7440-22-4	7.35 E-04	100.0	1000000	0.21	2074

**External Leadframe Plating**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	5.11 E-03	100.0	1000000	1.44	14417

**Bond Wires**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious Metals	Gold	7440-57-5	1.13E-03	99.00	990000	0.32	3196
Precious Metals	Palladium	7440-05-3	1.14E-05	1.00	10000	0.00	32
Subtotal			1.14E-03	100.00	1000000	0.32	3228

**Chip**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.62 E-02	100.0	1000000	4.56	45590

**Die Attach**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious Metals	Silver	7440-22-4	2.54E-03	75.47	754700	0.72	7171
Thermoset	Epoxy resin	Proprietary	6.35E-04	18.87	188700	0.18	1793
Other organic materials	Gamma Butyrolactone	96-48-0	9.53E-05	2.83	28300	0.03	269
Others	Curing agent & hardener	Proprietary	9.53E-05	2.83	28300	0.03	269
Subtotal	Subtotal		3.37 E-03	100.00	1000000	0.95	9501

<b>Package Totals</b>			<b>Weight (g)</b>			<b>Percentage (%)</b>	<b>PPM</b>
			3.54 E-01			100.00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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